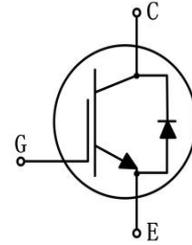


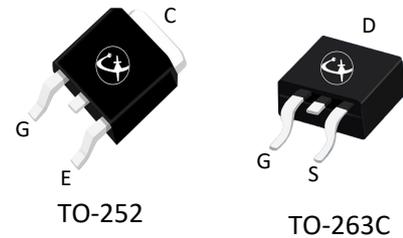
MAIN CHARACTERISTICS

I_C @TC=100°C	10A
V_{CE}	650V
$V_{GE(th)}$	5.8V
$V_{CE(sat)}$ -typ	1.8V



FEATURES

- Trench and field-stop technology
- Low switching losses
- Positive temperature coefficient
- Low Gate-Charge
- RoHS compliant



APPLICATIONS

- UPS
- Motor drives
- Boost
- PFC

MECHANICAL DATA

- Case: Molded plastic
- Mounting Position: Any
- Molded Plastic: UL Flammability Classification Rating 94V-0
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Solder bath temperature 275°C maximum, 10s per JESD 22-B106

Product specification classification

Part Number	Package	Mode Name	Pack
LGT10N65D	TO-252	LGT10N65D	Tape
LGT10N65T	TO-263C	LGT10N65T	Tape

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CES}	650	V
Gate-emitter voltage	V_{GES}	± 20	V
Continuous collector current (TC=25°C)	I_c	20	A
Continuous collector current (TC=100°C)		10	A
Pulsed collector current, tp limited by Tvjmax	I_{CM}	40	A
Diode continuous forward current (TC=100°C)	I_F	10	A
Diode maximum current, tp limited by Tvjmax	I_{FM}	40	A
Short Circuit with Stand Time $V_{GE}=15V, V_{CC} \leq 400V$, Allowed Number of Short Circuits < 1000, Times Between Short Circuits $\geq 1.0s$, $T_J \leq 175^\circ C$	t_{sc}	10	μS
Power dissipation (TC=25°C)	P_{tot}	100	W
Power dissipation (TC=100°C)		50	W
Operating junction temperature range	T_{Jmax}	-40 to +175	°C
Storage temperature range	T_{Stg}	-55 to +150	°C

Thermal characteristics

Parameter	Symbol	Values	Unit
Thermal resistance, junction to case for IGBT	$R_{th(j-c)}$	1.5	K/ W
Thermal resistance, junction to case for Diode	$R_{th(j-c)}$	2	K/ W
Thermal resistance, junction to ambient	$R_{th(j-a)}$	62	K/ W

Note1: Pulse test: 300 μs pulse width, 2 % duty cycle

Electrical characteristics of IGBT at $T_{vj}=25^\circ C$ unless otherwise specified

Static characteristics

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit
Collector-emitter breakdown voltage	$V_{GE}=0V, I_c=250\mu A$	BV_{CES}	650	-	-	V
Collector-emitter leakage current	$V_{CE}=650V, V_{GE}=0V$	I_{CES}	-	-	50	μA
Gate leakage current, forward	$V_{GE}=\pm 20V, V_{CE}=0V$	I_{GES}	-	-	± 100	nA
Gate-emitter threshold voltage	$V_{GE}=V_{CE}, I_c=250\mu A$	$V_{GE(th)}$	5.5	5.8	6.2	V
Collector-emitter saturation voltage	$V_{GE}=15V, I_c=10A, T_{vj}=25^\circ C$	$V_{CE(sat)}$	-	1.8	-	V
	$V_{GE}=15V, I_c=10A, T_{vj}=150^\circ C$		-	2.1	-	V
Diode forward voltage	$I_F=10A, T_{vj}=25^\circ C$	V_F	-	1.4	-	V
	$I_F=10A, T_{vj}=150^\circ C$		-	1.2	-	V

Electrical characteristics of IGBT at $T_{vj}=25^{\circ}\text{C}$ unless otherwise specified

Dynamic characteristics

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit
Input capacitance	$V_{CE}=30\text{V}$	C_{ies}	-	667	-	pF
Output capacitance	$V_{GE}=0\text{V}$	C_{oes}	-	35	-	pF
Reverse transfer capacitance	$f=1\text{MHz}$	C_{res}	-	9	-	pF
Total gate charge	$V_{CC}=520\text{V}$ $V_{GE}=15\text{V}$ $I_C=10\text{A}$	Q_g	-	27	-	nC

Switching characteristics

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit	
Turn-on delay time	$V_{CC}=400\text{V}$ $V_{GE}=15\text{V}$ $I_C=10\text{A}$ $R_G=10\Omega$ Inductive load	$t_{d(on)}$	-	11	-	ns	
Rise time		t_r	-	9	-	ns	
Turn-off delay time		$t_{d(off)}$	-	69	-	ns	
Fall time		t_f	-	73	-	ns	
Turn-on energy		E_{on}	-	0.18	-	mJ	
Turn-off energy		E_{off}	-	0.17	-	mJ	
Total switching energy		E_{ts}	-	0.35	-	mJ	
Turn-on delay time		$V_{CC}=400\text{V}$ $V_{GE}=15\text{V}$ $I_C=10\text{A}$ $R_G=10\Omega$ Inductive load $T_{vj}=150^{\circ}\text{C}$	$t_{d(on)}$	-	9	-	ns
Rise time			t_r	-	11	-	ns
Turn-off delay time			$t_{d(off)}$	-	85	-	ns
Fall time	t_f		-	111	-	ns	
Turn-on energy	E_{on}		-	0.21	-	mJ	
Turn-off energy	E_{off}		-	0.25	-	mJ	
Total switching energy	E_{ts}		-	0.46	-	mJ	

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit
Diode reverse recovery time	$V_R=400\text{V}$	t_{rr}	-	55	-	ns
Diode peak reverse recovery current	$I_F=10\text{A}$	I_{rrm}	-	11	-	A
Diode reverse recovery charge	$diF/dt=-750\text{A}/\mu\text{s}$	Q_{rr}	-	409	-	nC
Diode reverse recovery time	$V_R=400\text{V}$	t_{rr}	-	117	-	ns
Diode peak reverse recovery current	$I_F=10\text{A}$	I_{rrm}	-	11	-	A
Diode reverse recovery charge	$diF/dt=-750\text{A}/\mu\text{s}$ $T_{vj}=150^{\circ}\text{C}$	Q_{rr}	-	727	-	nC

RATINGS AND CHARACTERISTIC CURVES

Figure 1 Typical output characteristic($T_{vj}=25^{\circ}\text{C}$)

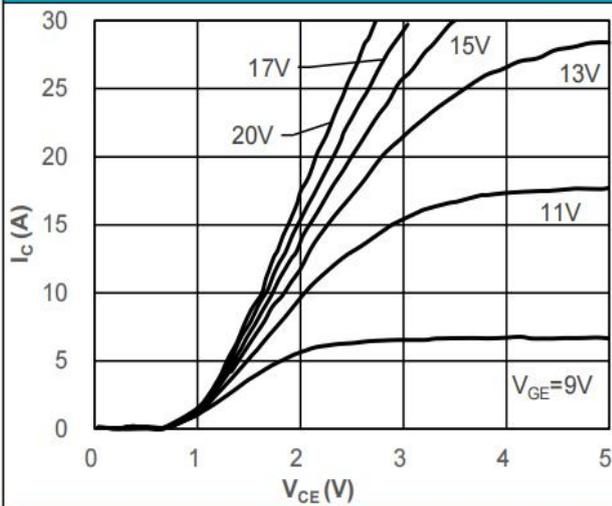


Figure 2 Typical output characteristic($T_{vj}=175^{\circ}\text{C}$)

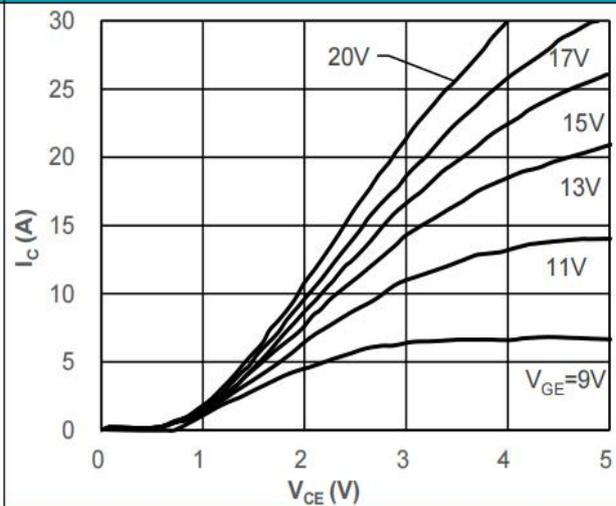


Figure 3 Power dissipation as a function of T_c

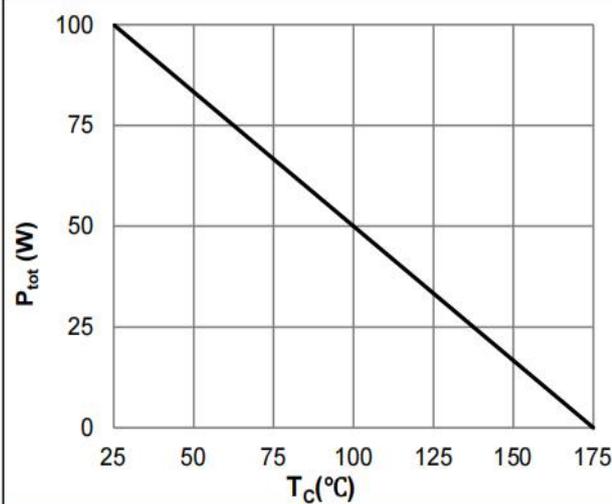


Figure 4 Typical Gate charge

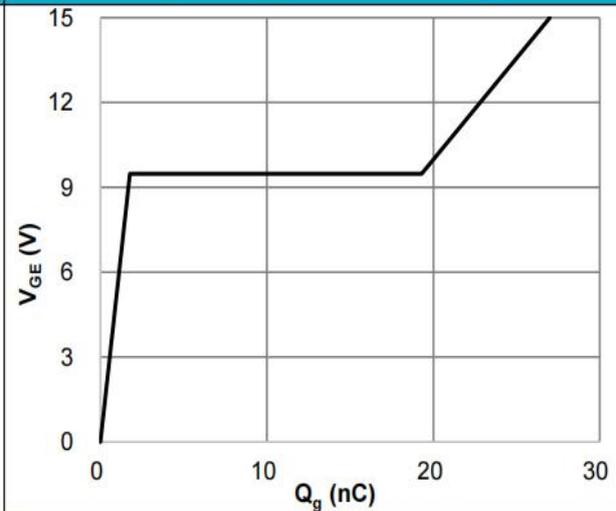


Figure 5 Typical $V_{GE(th)}$ as a function of $T_{vj}(I_c=1\text{mA})$

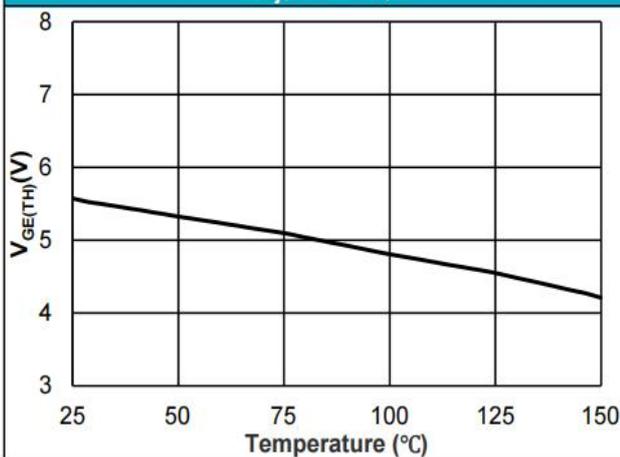
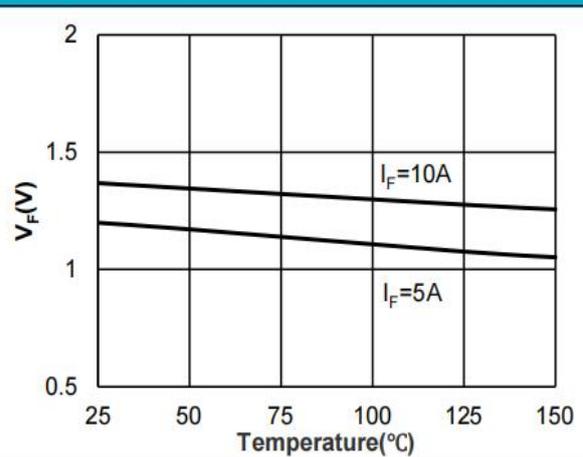


Figure 6 Typical V_F as a function of T_{vj}



RATINGS AND CHARACTERISTIC CURVES

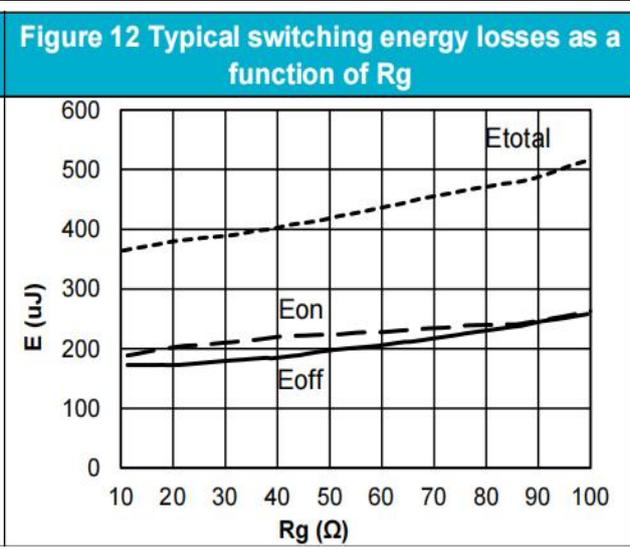
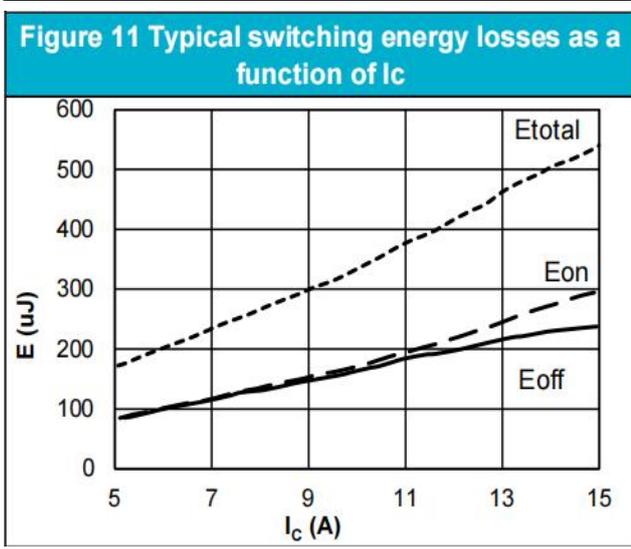
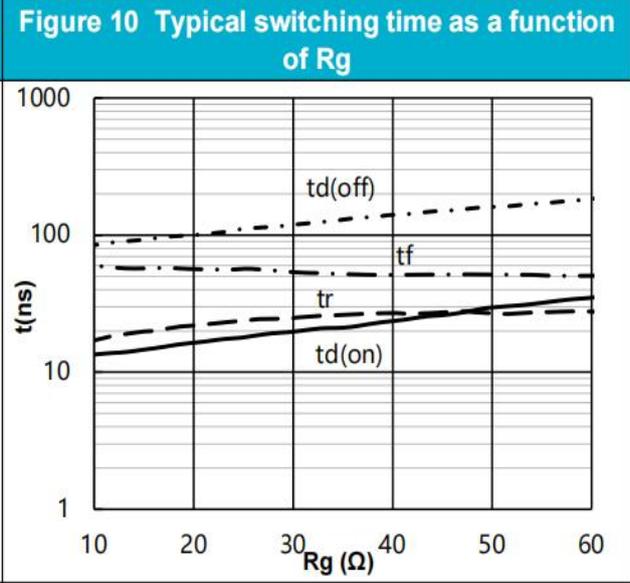
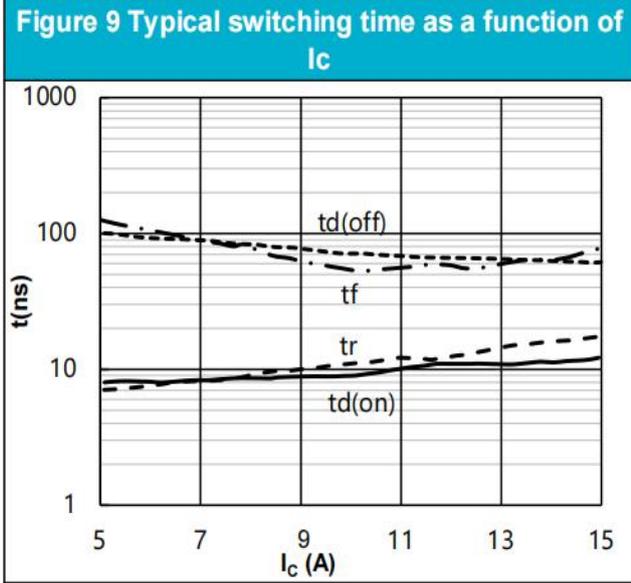
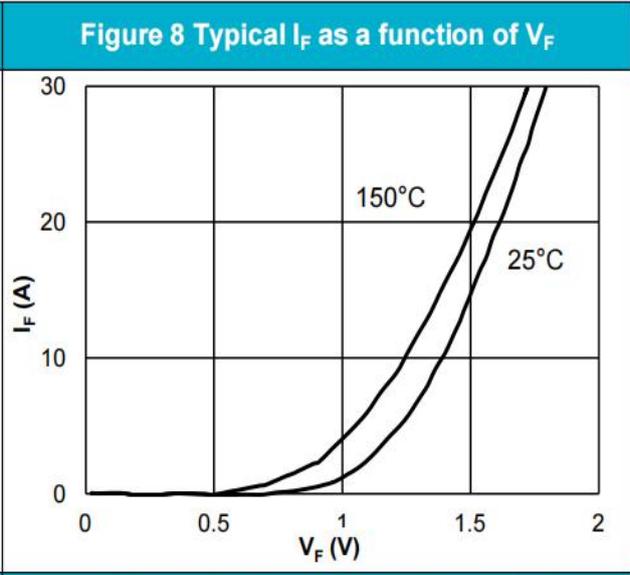
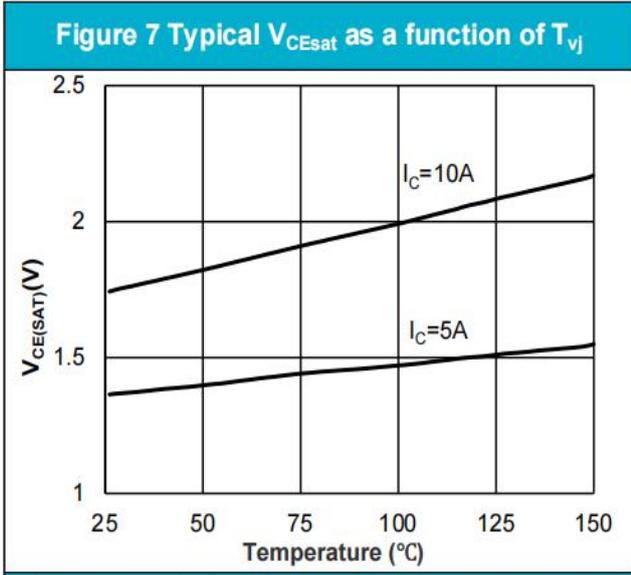
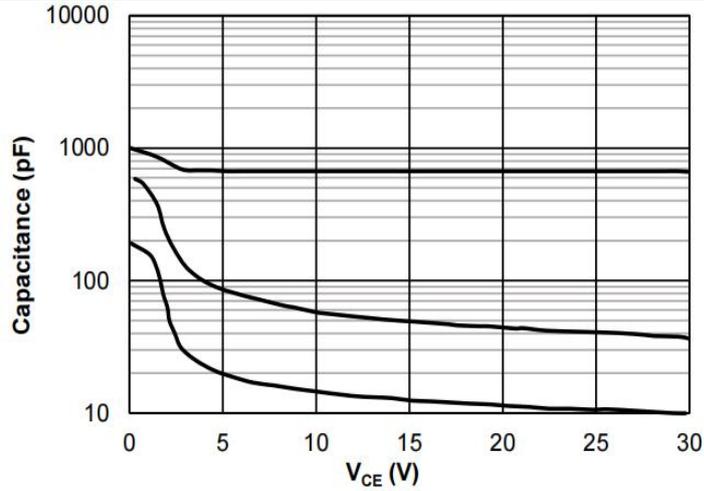
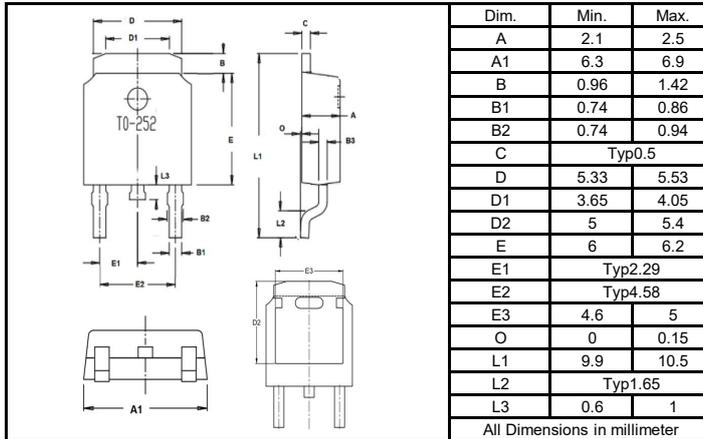


Figure 13 Typical capacitance as a function of VCE (f=1Mhz, VGE=0V)

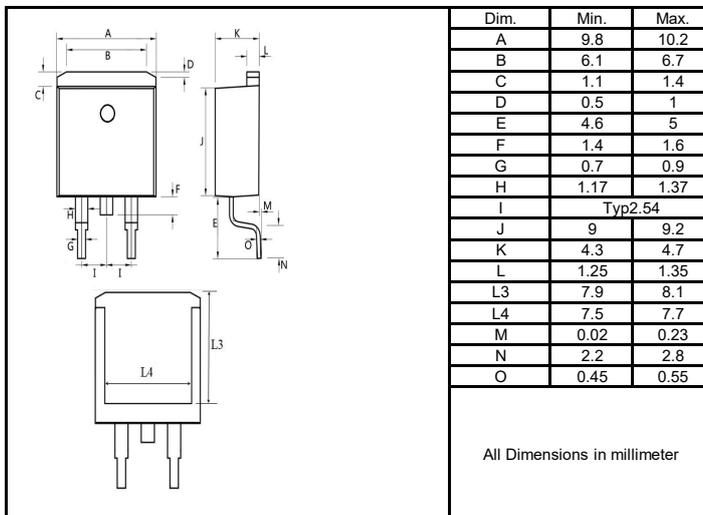


Package Outline Dimensions millimeters

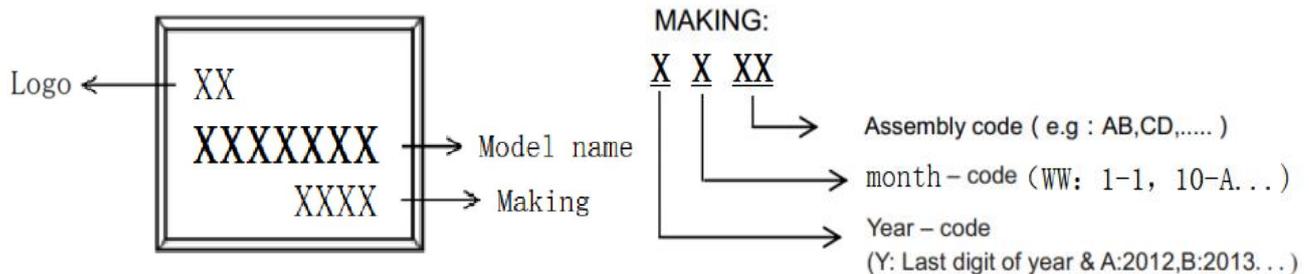
T0-252



T0-263C



Marking on the body



packing instruction

PKG	Minimal Package	Mini Box	Box
TO-252			
	2500pcs/disk	5000pcs/disk	25000pcs/box

TO-263C			
	800pcs/disk	1600pcs/disk	8000pcs/box



LGT10N65D/T

N-Channel Enhancement Mode Power IGBT

Notice

All product, product specifications and data are subject to change without notice to improve. The right to explain is owned by LINGXUN electronics company.

Confirm that operation temperature is within the specified range described in the product specification. Avoid applying power exceeding normal rated

power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

LINGXUN electronics shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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Revision History

Rev	Changes	Date
1.0	First version	2025-8-27
1.1	Add 263C packaging	2025-9-11